

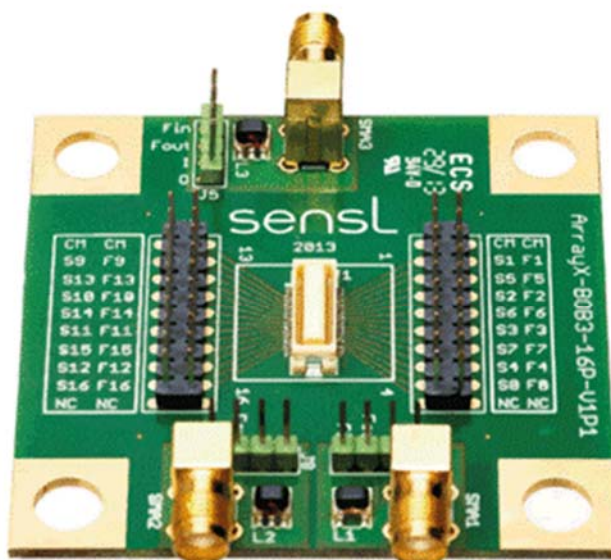


ARRAYX-BOB3-16P-GEVK: C-Array 3mm 4x4 BOB

The ArrayX-BOB3-16P is an evaluation board allowing easy access to the signals from a SensL ArrayC-30035-16P, 3mm 4x4 SiPM array. See Figure 7 for details on orientating the array correctly on the BOB.

The Breakout Board has a centrally located Hirose 40-way connector DF17(2.0)-40DS-0.5V(57). This connector mates with the Hirose DF17(2.0)-40DP-0.5V(57) board-to-board connector on the ArrayC-30035-16P. All signals on the array are routed via the mating connector to header pins. These pins are formed by two 20-way (10x2 row) 2.54mm pitch headers; J2 and J3.

Three SMA connectors and Balun transformers are provided with 4-pin headers to allow any signal to be connected directly to the SMA or via the transformer using jumper wires. Four 7mm holes are aligned on a 25mm grid to allow mounting of the board on an optical breadboard.



Evaluation/Development Tool Information

Product	Status	Compliance	Short Description	Parts Used	Action
ARRAYX-BOB3-16P-GEVK	Active		C-Array 3mm 4x4 BOB	ARRAYC-30035-16P-PCB	Contact Local Sales Office